

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S36	1	10/508917	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/04/24 08:55
S35	1	10/508917	US-PGPUB; USPAT	OR	ON	2008/04/24 08:55
S37	1	S36 and (molecul\$4 with glu\$3)	US-PGPUB; USPAT	OR	ON	2008/04/24 08:56
S38	1	"6214733".pn.	US-PGPUB; USPAT	OR	ON	2008/04/24 09:04
S39	2	(156/230-247 156/289).ccls. and (molecul\$3 with glu \$3) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 09:10
S43	48	(molecul\$3 near3 glu \$3) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 09:15
S42	67	(molecul\$3 with glu \$3) and (transfer\$4 with (device semiconductor chip))	USPAT	OR	ON	2008/04/24 09:15
S44	17	(molecul\$3 near3 glu \$3) and adhesive and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 09:26
S45	136	((molecul\$3 near3 (glu\$3 bond\$3)) same adhesive) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 09:27

S46	87	((molecule\$3 near3 (glu\$3 bond\$3)) with adhesive) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 09:28
S48	27	S46 and ((thermal\$2 heat\$3) same (molecule\$3 near3 (glu\$3 bond\$3)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 10:04
S49	12	S46 and ((thermal\$2 heat\$3) same (molecule\$3 near3 (glu\$3 bond\$3)))	USPAT	OR	ON	2008/04/24 10:12
S50	37	S46 and (thermal\$4 heat\$4)	USPAT	OR	ON	2008/04/24 10:23
S52	6	((molecule\$3 near3 (glu\$3 bond\$3) same direct) same adhesive) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 10:24
S51	5	((molecule\$3 near3 (glu\$3 bond\$3) same direct) with adhesive) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 10:24
S53	136	((molecule\$3 near3 (glu\$3 bond\$3)) same adhesive) and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 10:25
S55	45	S53 and ((thermal\$2 heat\$3) same (molecule\$3 near3 (glu\$3 bond\$3)))	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 10:26

S54	121	S53 and (thermal\$4 heat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/24 10:26
S57	13	S56 and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 10:39
S56	330	("156").clas. and ((thermal\$2 heat\$3) same (molecul\$3 near3 (glu\$3 bond \$3)))	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 10:39
S59	13	S57 and (transfer\$4 with (device semiconductor chip))	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 10:41
S58	341	("156").clas. and ((thermal\$2 reinforce\$3 heat\$3) same (molecul\$3 near3 (glu\$3 bond\$3)))	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/24 10:41
S60	1	"6214733".pn. and (polish\$4 flat smooth)	US-PGPUB; USPAT	OR	ON	2008/04/24 10:56

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